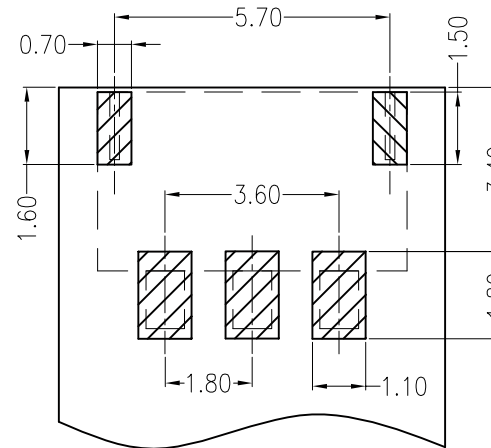
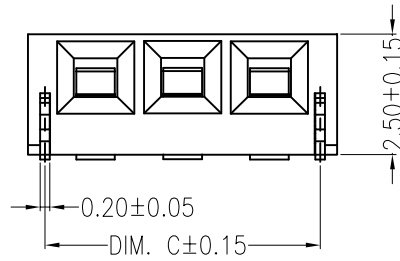
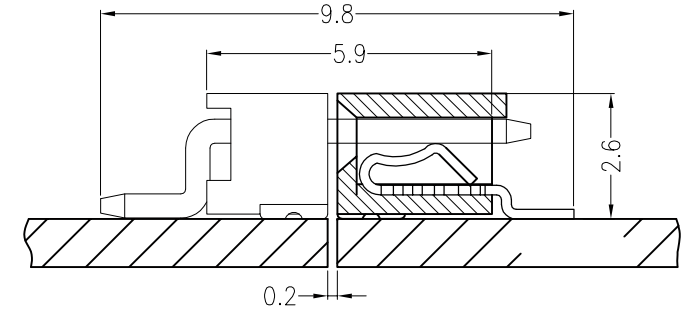
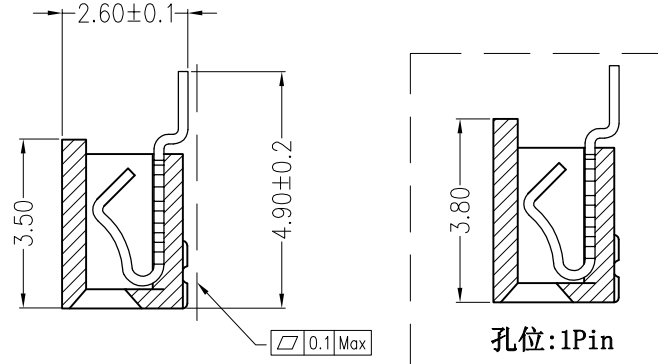
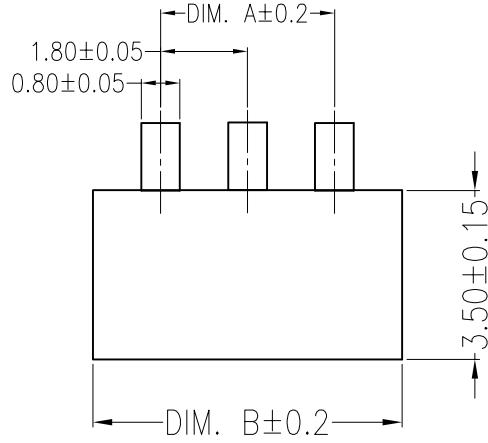


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2017.03.23



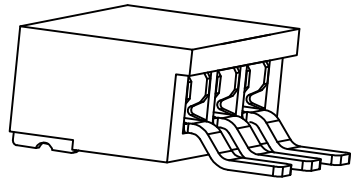
Assembly Layout

主要技术参数 Main Specifications

- 接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 800\text{M}\Omega$
- 额定电压 (Rated voltage): 125V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐电压 (Withstand Voltage): 800V AC/minute
- 温度范围 (Temperature Range): $-25^{\circ}\text{C} \sim +105^{\circ}\text{C}$



Mating Aluminum plate detail



	DIM.A	DIM.B	DIM.C
01		B=2.80	C=2.10
02	A=1.80	B=4.60	C=3.90
03	A=3.60	B=6.40	C=5.70
04	A=5.40	B=8.20	C=7.50
03(2)	A=3.60	B=6.40	C=5.70
04(2)	A=5.40	B=8.20	C=7.50
04(3)	A=5.40	B=8.20	C=7.50

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	SOLDER TAB	2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT	1~4 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

LEDsconn			TITLE: -
X.±0.5	X.±5'	USE: CUSTOMER	1.8mmPITCH 90°WAFER SMT TYPE
.X±0.3	.X±2'	APPD: 邵敬和	PART NO.:
.XX±0.25	.XX±1'	CHKD: 田峰	DWG NO.:
--	--	DR: 吴丹平	SCALE 1 : 1
UNITS: mm			SHEET 1 / 1